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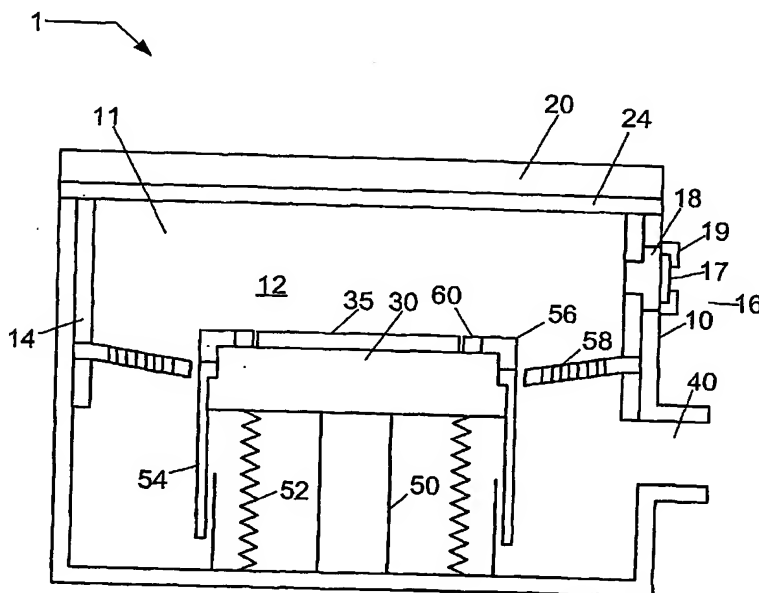
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(54) Title: A BARRIER LAYER FOR A PROCESSING ELEMENT AND A METHOD OF FORMING THE SAME



(57) Abstract: In order to mitigate erosion of exposed processing elements in a processing system by the process and any subsequent contamination of the substrate in the processing system, processing elements exposed to the process are coated with a protective barrier. The protective barrier comprises a protective layer that is resistant to erosion by the plasma, and a bonding layer that improves the adhesion of the protective layer to the processing element to mitigate possible process contamination by failure of the protective layer.

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